

MPSW01 NPN General Purpose Amplifier

Features

- This device is designed for general purpose medium power amplifiers
- Sourced from process 37



Absolute Maximum Ratings * $T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
VCEO	Collector-Emitter Voltage	30	V
Vсво	Collector-Base Voltage	40	V
Vebo	Emitter-Base Voltage	5.0	V
lc	Collector Current - Continuous	1.0	A
P _D Total Device Dissipation Derate about 25°C		1.0 8.0	W mW/°C
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to +150	٥C

* These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Note :

1) These ratings are based on a maximum junction temperature 150 'C

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case*	50	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambien*	125	°C/W

* Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6cm²

Symbol	Parameter	Test Condition	MIN	MAX	Units
Off Charac	teristics				
V(BR)CEO	Collector-Emitter Breakdown Voltage	Ic = 10 mA, I _B = 0	30		V
V(BR)CBO	Collector-Base Breakdown Voltage	Ic = 100 uA, IE = 0	40		V
V(BR)EBO	Emitter-Base Breakdown Voltage	IE = 100 uA, Ic = 0	5.0		V
Ісво	Collector-Cutoff Current	Vcb = 30 V, IE = 0		0.1	uA
Іево	Emitter-Cutoff Current	V _{EB} = 3.0 V, Ic = 0		0.1	uA
On Charac	teristics				
hfe	DC Current Gain	Ic = 10 mA, Vce = 1.0 V	55		
		Ic = 100 mA, Vce = 1.0 V	60		
		Ic = 1.0 A, Vce = 1.0 V	50		
Vce(sat)	Collector-Emitter Saturation Voltage *	Ic = 1.0A, I _B = 100 mA		0.5	V
V _{BE(on)}	Emitter-Base On Voltage *	Ic = 1.0A, Vce = 1.0 V		1.2	V

Small Signal Characteristics

fт	Small-Signal Current Gain	Ic = 50 mA, Vce = 10 V, f = 20 MHz	50		MHz
Ccb	Collector-Base Capacitance	$V_{CB} = 10 V$, $I_E = 0$, $f = 1.0 MHz$		20	pF

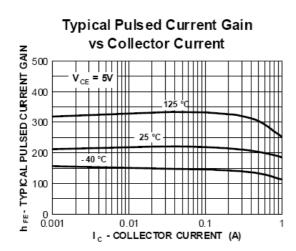
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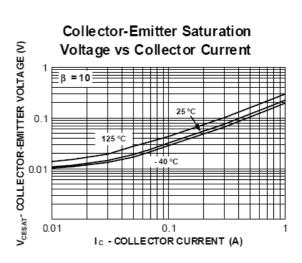
1) These ratings are based on a maximum junction temperature 150 $\ensuremath{^{\circ}C}$

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

3) *Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1.0%

Typical Characteristics



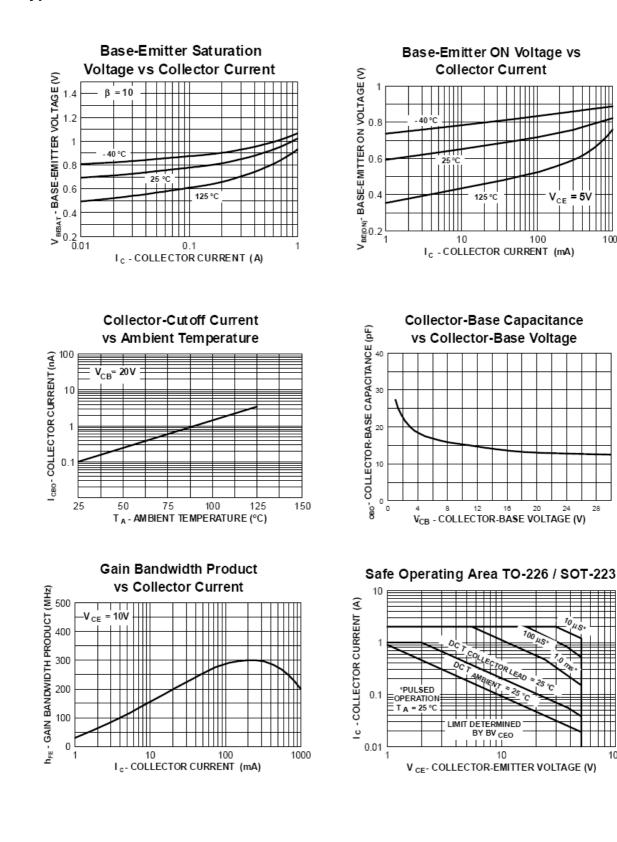




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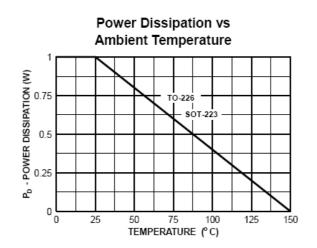
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Typical Characteristics (continued)



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Typical Characteristics (continued)



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